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Patent Claims

1. Carrier member composed of a ceramic for electronic components having at least two contact surfaces (2) electrically insulated from one another, whereby the contact surfaces are arranged on a common plane of the carrier member, characterized in that further metallized surfaces (3) are located on at least one surface of the carrier member that does not proceed parallel to the common plane of the contact surfaces (2), whereby a respective metallized surface is conductively connected to one of the contact surfaces.

2. Carrier member according to claim 1, characterized in that the carrier member comprises a roof element (13), whereby an inductive component (17) is arranged on the inside surface of the roof element (11).

3. Carrier member according to claim 1 or 2, characterized in that the surfaces that do not proceed parallel to the common plane of the contact surfaces (2) and on which the metallized surfaces (3) are located proceed at an angle of 90° relative to the common plane of the contact surfaces (2).

4. Carrier member according to at least one of the claims 1 through 3, characterized in that the carrier member comprises two walls (12) proceeding at an angle of 90° relative to the common plane of the contact surfaces (2), a roof element (13) that is arranged perpendicular to the walls and parallel to the common plane of the contact surfaces (2), and two end walls (5) that are arranged perpendicular to the roof element and the walls.

5. Carrier member according to at least one of the claims 1 through 4, characterized in that channel-shaped depressions (4) are situated between the metallic contact surfaces (2) and the metallized surfaces (3), whereby the channel-shaped depressions are not metallized.

6. Carrier member according to claim 5, characterized in that channel-shaped depressions (4) are arranged on the common plane of the contact surfaces (2) and further channel-shaped depressions (4) are located on the planes that do not proceed parallel to the common plane of the contact surfaces, whereby these depressions (4) arranged on various planes form channel edges (15).

Summary 7. Carrier member according to at least one of the claims 1 through 6, characterized in that a lead (7) is electrically conductively connected to a metallized surface (3).

5 8. Carrier member according to at least one of the claims 1 through 7, characterized in that the channel edge guides a lead (7) such that the lead experiences a mechanical localization in the channel edges (15).

9. Carrier member according to claim 8, characterized in that the lead (7) guided by the channel edge (15) is conductively connected to a metallized surface (3) immediately adjacent to the corresponding channel-shaped depression.

10 10. Carrier member according to at least one of the claims 1 through 9, characterized in that the co-planarity of the plane-parallel contact surfaces (2) amounts to less than 100 μm , whereby the co-planarity is the maximum spacing from a plane that lies parallel to the contact surfaces (2) and that has been calculated from the individual heights of the contact surfaces (2).

15 11. Carrier member according to at least one of the claims 1 through 10, characterized in that a roof element (13) proceeding parallel to the common plane of the contact surfaces (2) is present, and a conical frustum (10) is arranged on the inside surface of the roof element (11) in the direction of the interior (6).

20 12. Carrier member according to at least one of the claims 1 through 11, characterized in that a roof element (13) proceeding parallel to the common plane of the contact surfaces (2) is present, and a core (9) with a winding (14) is arranged on the inside surface of the roof element (11) in the direction of the interior.

13. Electronic component, characterized in that it contains a carrier member according to claim 1.

25 14. Employment of the carrier element according to claim 1 for inductive components.

Method of manufacturing an electronic component (13) comprising the steps of fastening an inductive component (14) on the inside surface of a carrier member according to claim 1;

30 -- guiding the wires (7) of the inductive component over the channel edges (15).

- guiding the wires (7) at an angle over the contact surface (4);
- contacting the wire (7) to the metallized surface and potentially removing the wire ends projecting beyond the contact surfaces (8).